

N-Channel MOSFET

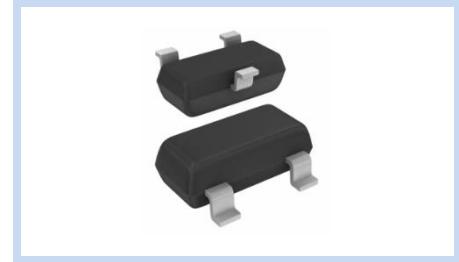
100V 200mA 0.5W SOT-23 ESD

MFT10NA20S23E

MERITEK

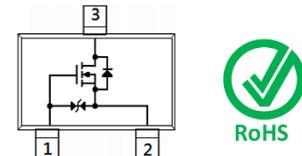
FEATURE

- $R_{DS(ON)} \leq 6\Omega$, $V_{GS} = 10V$, $I_D = 190mA$
- $R_{DS(ON)} \leq 10\Omega$, $V_{GS} = 4.5V$, $I_D = 150mA$
- ESD Protected Gate
- Low Input Capacitance
- Application: DC-DC Converters, Switch Load, PWM, Motor Control



MECHANICAL DATA

- Case: SOT-23 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

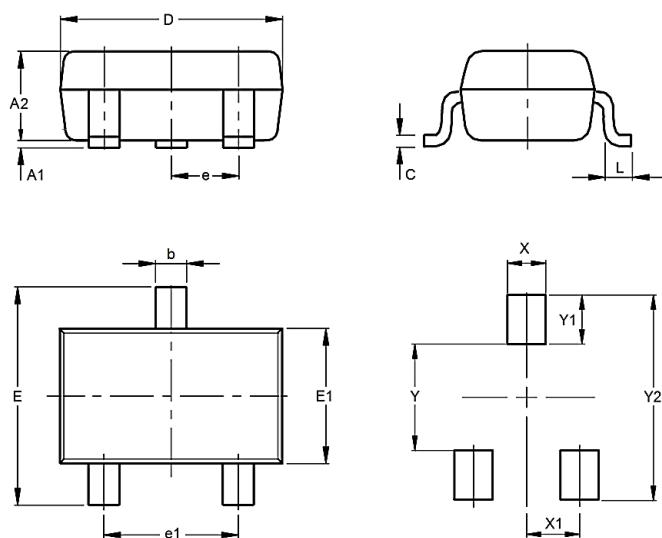


MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current – Continuous		I_D	200	mA
Drain Current – Pulsed	Note 1	I_{DM}	600	mA
Power Dissipation		P_D	500	mW
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C
Thermal Resistance, Junction to Ambient	Note 2	$R_{θJA}$	250	°C / W

DIMENSIONS

Item	Min (mm)	Max (mm)
A1	0.00	0.10
A2	0.79	1.40
b	0.30	0.50
c	0.08	0.20
D	2.70	3.10
e	0.89	1.02
e1	1.78	2.04
E	2.10	2.80
E1	1.20	1.60
L	0.15	--
X	0.80	
X1	0.95	
Y	1.40	
Y1	1.00	
Y2	3.40	



ELECTRICAL CHARACTERISTICS

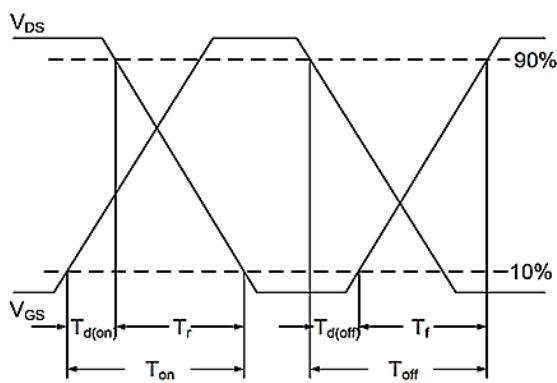
Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = 250\mu A$	BV_{DSS}	100	--	--	V
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D = 1mA$	$V_{GS(th)}$	1.5	--	2.5	V
Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	I_{GSS}	--	--	± 10	μA
Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS}=0V$	I_{DSS}	--	--	1	μA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 190mA$	$R_{DS(on)}$	--	--	6	Ω
	$V_{GS} = 4.5V, I_D = 150mA$		--	--	10	
Dynamic Characteristics	Conditions	Symbol	--	Typ.	Max	Unit
Gate resistance	$V_{DS}=0V, F=1MHz$	R_g	--	38	--	Ω
Input Capacitance	$V_{DS} = 50V, V_{GS}=0V, F=1MHz$	C_{iss}	--	39	--	pF
Output Capacitance		C_{oss}	--	10	--	
Reverse Transfer Capacitance		C_{rss}	--	6.6	--	
Turn-On Delay Time	$V_{DD} = 50V, I_D \geq 190mA, V_{GS} = 10V, R_G = 6\Omega$	$T_{d(on)}$	--	6.5	--	nS
Rise Time		T_r	--	7.5	--	
Turn-Off Delay Time		$T_{d(off)}$	--	10	--	
Fall Time		T_f	--	85	--	
Total Gate Charge	$V_{DS} = 30V, V_{GS} = 10V, I_D \geq 1A$	Q_g	--	1.5	--	nC
Gate-Source Charge		Q_{gs}	--	0.5	--	
Gate-Drain Charge		Q_{gd}	--	0.6	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Diode Forward Voltage	$I_S = 0.1A, V_{GS}=0V$	V_{SD}	--	--	1.2	V

Note:

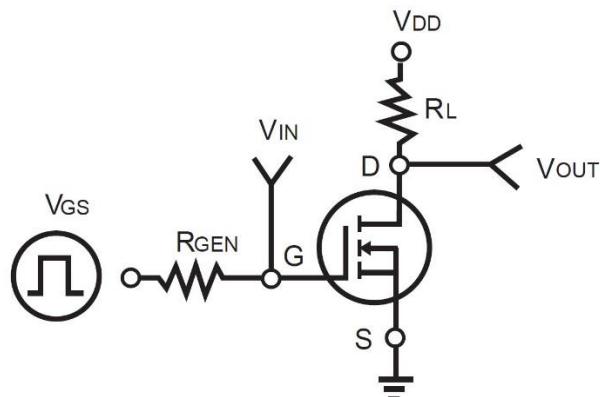
1. Pulse width<100 μs , Duty cycle<2%; Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}C$.

2. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

Switching Time Waveform

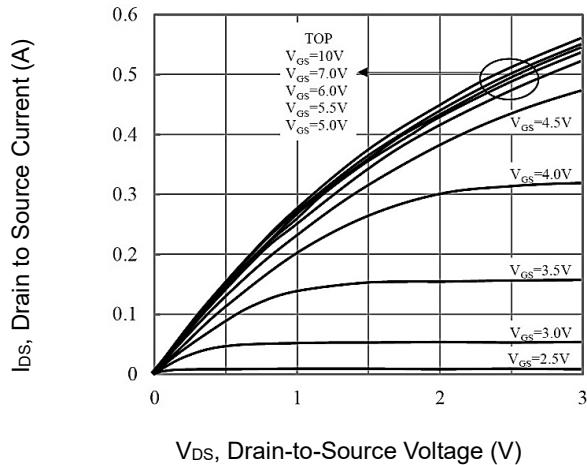


Switching Test Circuit

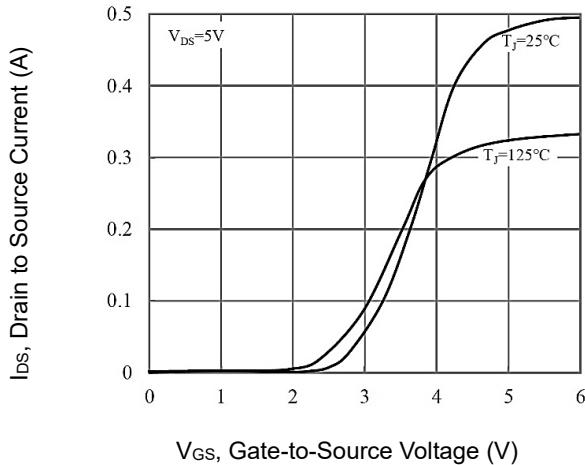


CHARACTERISTIC CURVES

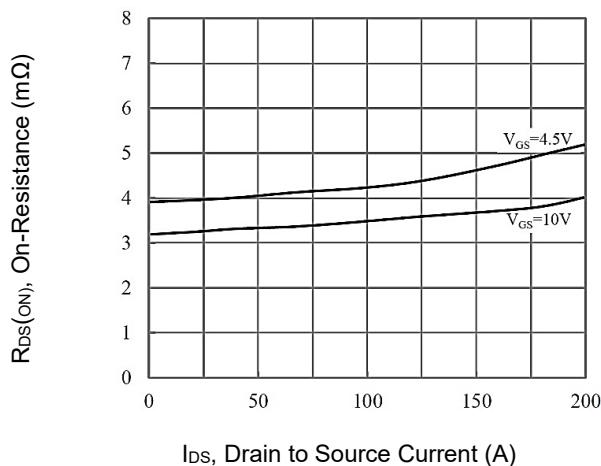
On Region Characteristics



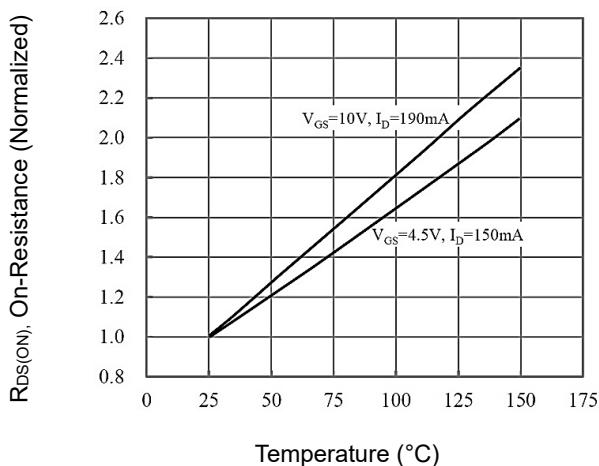
Transfer Characteristics



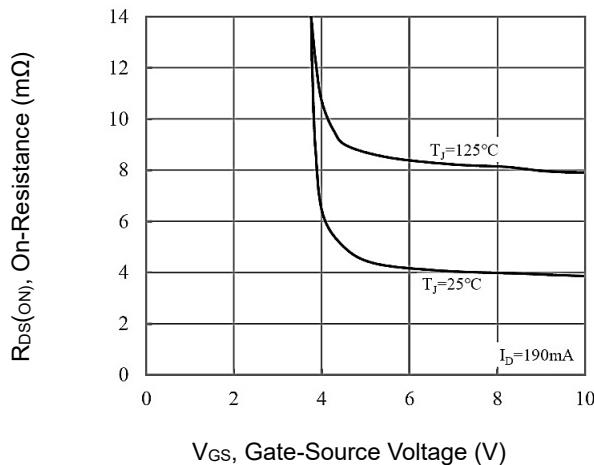
On-Resistance vs. Drain Current



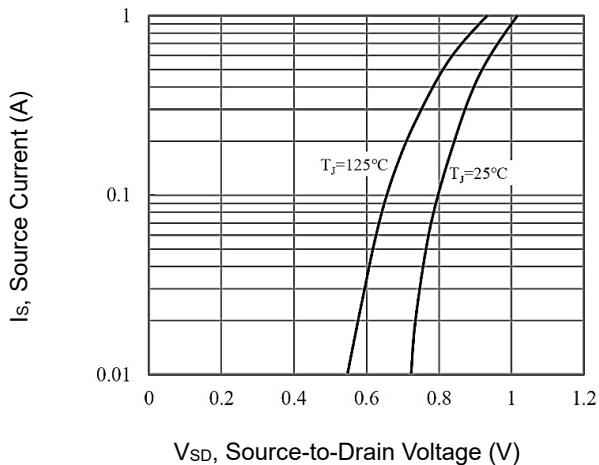
On-Resistance vs. Junction Temperature



On-Resistance Variation with V_{GS}

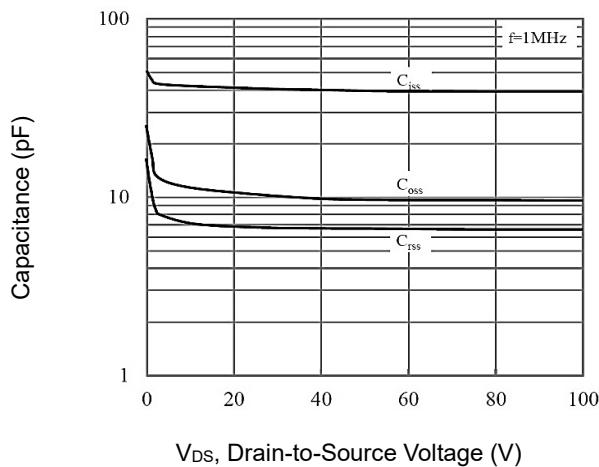


Body Diode Characteristics

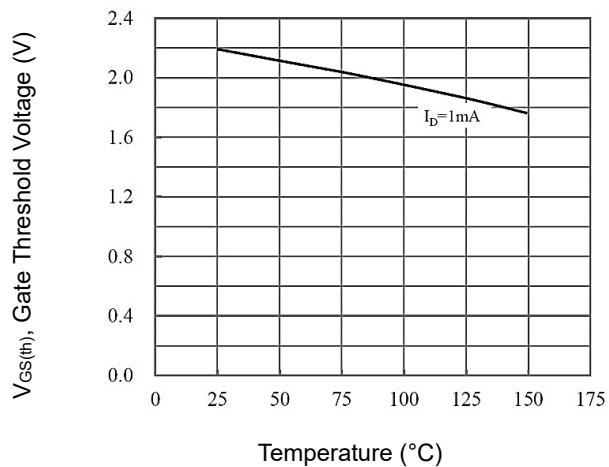


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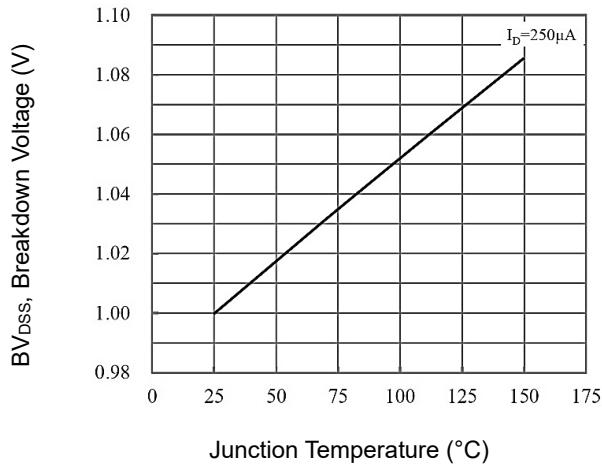
Capacitance vs. Drain-Source Voltage



Threshold Voltage Variance



Breakdown Voltage vs Junction Temperature



Safe Operating Area

